

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1119	(package and (leadframe lead adj frame)).clm.	US-PGPUB	OR	ON	2006/11/10 19:29
L2	976	(package and (leadframe lead adj frame) and (chip die ic integrated adj circuit)).clm.	US-PGPUB	OR	ON	2006/11/10 19:29
L3	561	(package and (leadframe lead adj frame) and (chip die ic integrated adj circuit) and (resin encapsulant sealant molded molding)).clm.	US-PGPUB	OR	ON	2006/11/10 19:30